Titanium FPGA Selector Guide

Enabling the AI-Driven World

They enable AI acceleration, data analysis, real-time decision making, and other compute-intensive workloads for applications such as machine vision, automotive, hand-held medical devices, and next-generation edge applications. They feature the innovative Quantum® compute fabric that, with its enhanced compute capability, makes Titanium FPGAs ideal for embedded hardware acceleration applications. With a wide range of logic element (LE) densities from 35K to 2M, and compatibility with the Efinix RISC-V SoCs, they can help you turn a tiny chip into an accelerated embedded compute system.

35K to 1,000K Logic Elements | 10 Kb Embedded RAM Blocks | DSP Blocks | PLLs | High-Voltage I/O (HVIO) | High-Speed I/O (HSIO) | Hardened RISC-V Block | MIPI D-PHY 2.5 Gbps | LPDDR4/4x Controller & PHY | Transceivers (Xcvr) 16G/25.8G

Titanium Ordering Codes

You can use HSIO pairs for a various differential standards such as LVDS (1.5 Gbps), differential HSTL/SSTL, or MIPI RX and TX data/clock lanes (1.5 Gbps).

FPGA	LEs	RAM (Mbits)	RAM Blocks (10 Kb)	DSP Blocks	Package	Pins	HVIO	HSIO	PLLs	2.5G MIPI D-PHY	Hardened RISC-V Block	LPDDR 4/4x	Xcvr [2] Banks	PCIe®	25.8G Xcvr	Temp.	Speed Grade	Ordering Code
Ti35	36,176	1.53	153	93	FBGA	100[1]	–	61	3	–	–	–	–	–	–	C	3, 3L, 4, 4L	Ti35F100C3/3L/4/4L
																		Ti35F100S3F2 C3/3L/4/4L
																I	3, 3L	Ti35F100I3/3L
																		Ti35F100S3F2I3/3L
						225	23	140	4	–	–	–	–	–	–	C	3, 3L, 4, 4L	Ti35F225C3/3L/4/4L
																I	3, 3L	Ti35F225I3/3L
						256	27	142	4	–	–	–	–	–	–	C	3, 3L, 4, 4L	Ti35F256C3/3L/4/4L
																I	3, 3L	Ti35F256I3/3L
Ti60	62,016	2.6	256	160	WLCSP	64	–	34	2	–	–	–	–	–	–	C	3	Ti60W64C3
																I	3	Ti60W64I3
																C	3	Ti60V64C3
																I	3	Ti60V64I3
					FBGA	100[1]	–	61	3	–	–	–	–	–	–	C	3, 3L, 4, 4L	Ti60F100C3/3L/4/4L
																		Ti60F100S3F2 C3/3L/4/4L
																I	3, 3L	Ti60F100I3/3L
																		Ti60F100S3F2I3/3L
						225	23	140	4	–	–	–	–	–	–	C	3, 3L, 4, 4L	Ti60F225C3/3L/4/4L
																I	3, 3L	Ti60F225I3/3L
																Q	3	Ti60F225Q3
						256	27	142	4	–	–	–	–	–	–	C	3, 3L, 4, 4L	Ti60F256C3/3L/4/4L
																I	3, 3L	Ti60F256I3/3L

FPGA	LEs	RAM (Mbits)	RAM Blocks (10 Kb)	DSP Blocks	Package	Pins	HVIO	HSIO	PLLs	2.5G MIPI D-PHY	Hardened RISC-V Block	LPDDR 4/4x	Xcvr [2] Banks	PCIe®	25.8G Xcvr	Temp.	Speed Grade	Ordering Code
Ti85	83,232	6.18	604	300	FBGA	441	20	88	9	1 TX 1 RX	Quad Core	x16	up to 2	1x Gen4	–	C	3, 3L, 4, 4L	Ti85N441C3/3L/4/4L
																I		Ti85N441I3/3L/4/4L
						484	21	85	8	1 TX 1 RX	Quad Core	x32	up to 2	1x Gen4	–	C	3, 3L, 4, 4L	Ti85N484C3/3L/4/4L
																I		Ti85N484I3/3L/4/4L
						576	34	100	9	2 TX 2 RX	Quad Core	x32	up to 2	1x Gen4	–	C	3, 3L, 4, 4L	Ti85N576C3/3L/4/4L
																I		Ti85N576I3/3L/4/4L
						676	84	139	9	2 TX 2 RX	Quad Core	x32	up to 2	1x Gen4	–	C	3, 3L, 4, 4L	Ti85N676C3/3L/4/4L
																I		Ti85N676I3/3L/4/4L
Ti90	92,534	6.88	688	336	FBGA	361	20	110	8	2 TX 2 RX	–	x16	–	–	–	C	3, 3L, 4, 4L	Ti90J361C3/3L/4/4L
																I		Ti90J361I3/3L/4/4L
						400	74	200	8	–	–	–	–	–	–	C	3, 3L, 4, 4L	Ti90G400C3/3L/4/4L
																I		Ti90G400I3/3L/4/4L
						484	27	116	8	4 TX 4 RX	–	x32	–	–	–	C	3, 3L, 4, 4L	Ti90J484C3/3L/4/4L
																I		Ti90J484I3/3L/4/4L
																Q	3	Ti90J484Q3
						529	48	210	8	–	–	x32	–	–	–	C	3, 3L, 4, 4L	Ti90G529C3/3L/4/4L
																I		Ti90G529I3/3L/4/4L
Ti120	123,379	9.18	918	448	FBGA	361	20	110	8	2 TX 2 RX	–	x16	–	–	–	C	3, 3L, 4, 4L	Ti120J361C3/3L/4/4L
																I		Ti120J361I3/3L/4/4L
						400	74	200	8	–	–	–	–	–	–	C	3, 3L, 4, 4L	Ti120G400C3/3L/4/4L
																I		Ti120G400I3/3L/4/4L
						484	27	116	8	4 TX 4 RX	–	x32	–	–	–	C	3, 3L, 4, 4L	Ti120J484C3/3L/4/4L
																I		Ti120J484I3/3L/4/4L
																Q	3	Ti120J484Q3
						529	48	210	8	–	–	x32	–	–	–	C	3, 3L, 4, 4L	Ti120G529C3/3L/4/4L
																I		Ti120G529I3/3L/4/4L
Ti135	132,192	9.83	960	480	FBGA	441	20	88	9	1 TX 1 RX	Quad Core	x16	up to 2	1x Gen4	–	C	3, 3L, 4, 4L	Ti135N441C3/3L/4/4L
																I		Ti135N441I3/3L/4/4L
						484	21	85	8	1 TX 1 RX	Quad Core	x32	up to 2	1x Gen4	–	C	3, 3L, 4, 4L	Ti135N484C3/3L/4/4L
																I		Ti135N484I3/3L/4/4L
						576	34	100	9	2 TX 2 RX	Quad Core	x32	up to 2	1x Gen4	–	C	3, 3L, 4, 4L	Ti135N576C3/3L/4/4L
																I		Ti135N576I3/3L/4/4L
						576[4]	50	118	9	2 TX 2 RX	Quad Core	x16	up to 2	1x Gen4	–	C	4	Ti135N576D2F4C4
																I	3	Ti135N576D2F4I3
						676	84	139	9	2 TX 2 RX	Quad Core	x32	up to 2	1x Gen4	–	C	3, 3L, 4, 4L	Ti135N676C3/3L/4/4L
																I		Ti135N676I3/3L/4/4L
Ti165	162,800	12.1	1,182	590	FBGA	484	20	85	9	1 TX 1 RX	Quad Core	x32	up to 2	1x Gen4	–	C	3, 3L, 4, 4L	Ti165N484C3/3L/4/4L
																I		Ti165N484I3/3L/4/4L
						529	51	176	12	–	Quad Core	x32	–	–	–	C	3, 3L, 4, 4L	Ti165C529C3/3L/4/4L
																I		Ti165C529I3/3L/4/4L
						900	50	168	12	0 TX 2 RX	Quad Core	2 x32	up to 4	2x Gen4	–	C	3, 3L, 4, 4L	Ti165N900C3/3L/4/4L
																I		Ti165N900I3/3L/4/4L
						1,156	103	234	12	3 TX 3 RX	Quad Core	2 x32	up to 4	2x Gen4	–	C	3, 3L, 4, 4L	Ti165N1156C3/3L/4/4L
																I		Ti165N1156I3/3L/4/4L

FPGA	LEs	RAM (Mbits)	RAM Blocks (10 Kb)	DSP Blocks	Package	Pins	HVIO	HSIO	PLLs	2.5G MIPI D-PHY	Hardened RISC-V Block	LPDDR 4/4x	Xcvr [2] Banks	PCIe®	25.8G Xcvr	Temp.	Speed Grade	Ordering Code
Ti180	176,256	13.11	1,280	640	FBGA	361	20	110	8	2 TX 2 RX	–	x16	–	–	–	C	3, 3L, 4, 4L	Ti180J361C3/3L/4/4L
																I		Ti180J361I3/3L/4/4L
						400	74	200	8	–	–	–	–	–	–	C	3, 3L, 4, 4L	Ti180G400C3/3L/4/4L
																I		Ti180G400I3/3L/4/4L
						484[3]	54	190	8	2 TX 2 RX	–	x16	–	–	–	C	4	Ti180J484D1C4
																I	3	Ti180J484D1I3
						484	27	116	8	4 TX 4 RX	–	x32	–	–	–	C	3, 3L, 4, 4L	Ti180J484C3/3L/4/4L
																I		Ti180J484I3/3L/4/4L
																Q	3	Ti180J484Q3
						529	48	210	8	–	–	x32	–	–	–	C	3, 3L, 4, 4L	Ti180G529C3/3L/4/4L
																I		Ti180G529I3/3L/4/4L
Ti240	236,888	17.62	1,721	860	FBGA	484	20	85	9	1 TX 1 RX	Quad Core	x32	up to 2	1x Gen4	–	C	3, 3L, 4, 4L	Ti240N484C3/3L/4/4L
																I		Ti240N484I3/3L/4/4L
						529	51	176	12	–	Quad Core	x32	–	–	–	C	3, 3L, 4, 4L	Ti240C529C3/3L/4/4L
																I		Ti240C529I3/3L/4/4L
						900	50	168	12	0 TX 2 RX	Quad Core	2 x32	up to 4	2x Gen4	–	C	3, 3L, 4, 4L	Ti240N900C3/3L/4/4L
																I		Ti240N900I3/3L/4/4L
						1,156	103	234	12	3 TX 3 RX	Quad Core	2 x32	up to 4	2x Gen4	–	C	3, 3L, 4, 4L	Ti240N1156C3/3L/4/4L
																I		Ti240N1156I3/3L/4/4L
Ti375	370,137	27.53	2,688	1,344	FBGA	484	20	85	9	1 TX 1 RX	Quad Core	x32	up to 2	1x Gen4	–	C	3, 3L, 4, 4L	Ti375N484C3/3L/4/4L
																I		Ti375N484I3/3L/4/4L
						529	51	176	12	–	Quad Core	x32	–	–	–	C	3, 3L, 4, 4L	Ti375C529C3/3L/4/4L
																I		Ti375C529I3/3L/4/4L
						900	50	168	12	0 TX 2 RX	Quad Core	2 x32	up to 4	2x Gen4	–	C	3, 3L, 4, 4L	Ti375N900C3/3L/4/4L
																I		Ti375N900I3/3L/4/4L
						1,156	103	234	12	3 TX 3 RX	Quad Core	2 x32	up to 4	2x Gen4	–	C	3, 3L, 4, 4L	Ti375N1156C3/3L/4/4L
																I		Ti375N1156I3/3L/4/4L

1. The F100 pin package is available as a regular package as well as a SIP that incorporates SPI flash and HyperRAM in addition to the FPGA.
2. Each transceiver bank has 4 lanes. All banks support SGMII, 10GBase-KR, and PMA Direct. 1 bank supports PCIe.
3. This package is a SIP that incorporates LPDDR4x DRAM in addition to the FPGA.
4. The Ti135 576-ball FBGA is offered as a standard FPGA package or as a SiP integrating SPI flash and LPDDR4 DRAM.

Note: The LPDDR4/4x PHY with memory controller (x32 width) can be configured as x16 width.

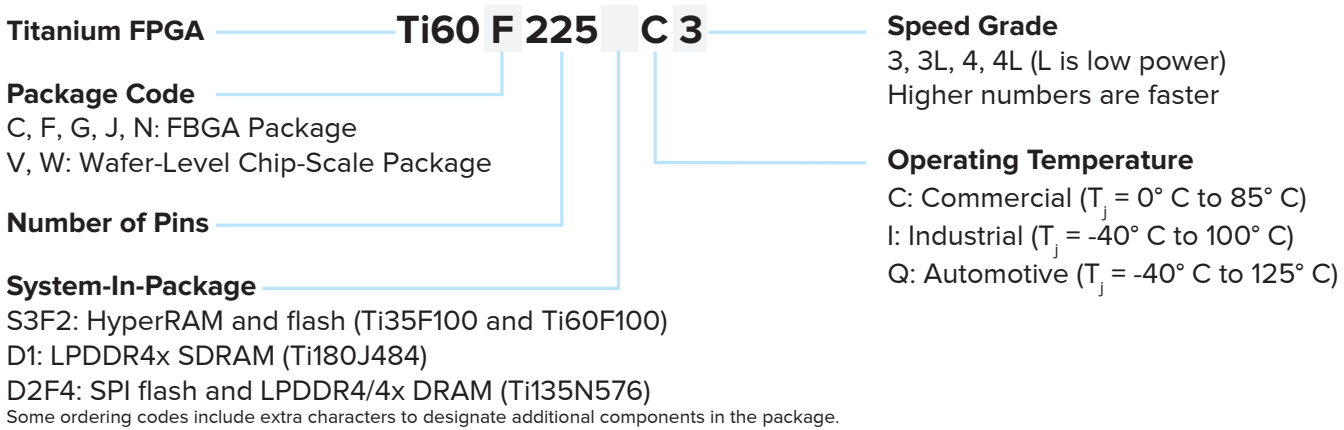
Package Dimensions

Package	Pitch (mm)	Dimensions (mm)
64-ball FBGA	0.4	3.5x3.4
100-ball FBGA	0.5	5.5x5.5
225-ball FBGA	0.65	10x10
256-ball FBGA	0.8	13x13
324-ball FBGA	0.8	15x15

Package	Pitch (mm)	Dimensions (mm)
361-ball FBGA	0.65	13x13
400-ball FBGA	0.8	16x16
441-ball FBGA	0.5	11x11
484-ball FBGA[3]	0.65	15x15
484-ball FBGA	0.8	18x18

Package	Pitch (mm)	Dimensions (mm)
529-ball FBGA	0.8	19x19
576-ball FBGA	0.65	16x16
676-ball FBGA	0.8	22x22
900-ball FBGA	0.8	25x25
1156-ball FBGA	1.0	35x35

Example Ordering Code



Product Longevity

Titanium products are designed into a broad range of applications in many diverse markets. Some of these markets are characterized by long product life cycles and, once in high volume production, are resistant to changes in specifications or components in the bill of materials. At Efinix we get that and are committed to supplying our customers with a stable supply of supported products throughout their product life cycle. We are committed to supporting our Titanium family of FPGAs in customer designs until at least 2045. Contact your local sales representative for more information on product life cycles.